

**N-Ch MOSFET** 

## **General Description**

The WSD2018DN22 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WSD2018DN22 meet the RoHS and Green Product requirement with full function reliability approved.

#### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

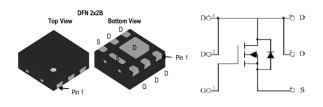
## **Product Summery**

BVDSS	RDSON	ID
20V	$15m\Omega_{(MAX)}$	12A

## Applications

- High Frequency Point-of-Load Synchronous s Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

## DFNWB2×2-6L-J Pin Configuration



## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
V <sub>DS</sub>	Drain-Source Voltage	20	V	
V <sub>GS</sub>	Gate-Source Voltage	±10	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	12	A	
I <sub>D</sub> @T <sub>C</sub> =70℃	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	10	A	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	40	А	
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>3</sup>	1.5	W	
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range -55 to 150		°C	

## **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit	
R <sub>eja</sub>	Thermal Resistance Junction-ambient <sup>1</sup>		167	°C/W	
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		65	°C/W	



N-Ch MOSFET

# Electrical Characteristics (T<sub>J</sub>=25<sup>-1</sup>C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	20			V	
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\!{\rm C}$ , I_D=1mA		0.027		V/℃	
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =5A		10	15	mΩ	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =2.5V , I <sub>D</sub> =5A		13	18		
		V <sub>GS</sub> =1.8V , I <sub>D</sub> =5A		18	30		
V <sub>GS(th)</sub>	Gate Threshold Voltage		0.4	0.7	1.0	V	
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	—V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA		2.56		mV/℃	
	Durin Course Lookage Current	$V_{DS}$ =16V , $V_{GS}$ =0V , $T_{J}$ =25 $^{\circ}$ C			1	uA	
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5		
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm12V$ , $V_{DS}=0V$			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =4V , I <sub>D</sub> =9.7A	20			S	
Rg	Gate Resistance	f=1MHz		2.5		Ω	
Qg	Total Gate Charge (4.5V)				32		
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =4V , V <sub>GS</sub> =5V , I <sub>D</sub> =10A		2.5		nC	
Q <sub>gd</sub>	Gate-Drain Charge			6.5			
T <sub>d(on)</sub>	Turn-On Delay Time			12	20		
Tr	Rise Time	$V_{DD}$ =4V , $V_{GS}$ =4.5V , $R_{G}$ =1 $\Omega$		10	25		
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =10A ,RL=0.4Ω		65	70	ns	
T <sub>f</sub>	Fall Time			20	60		
Ciss	Input Capacitance			1800			
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =4V , V <sub>GS</sub> =0V , f=1MHz		650		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			450			

#### Notes :

1.Surface mounted on FR4 board using 1 square inch pad size,1oz copper.

2.Surface mounted on FR4 board using the minimum pad size,1oz copper.

3. Pulse test : Pulse width=300 $\mu$ s, duty cycle≤2%.

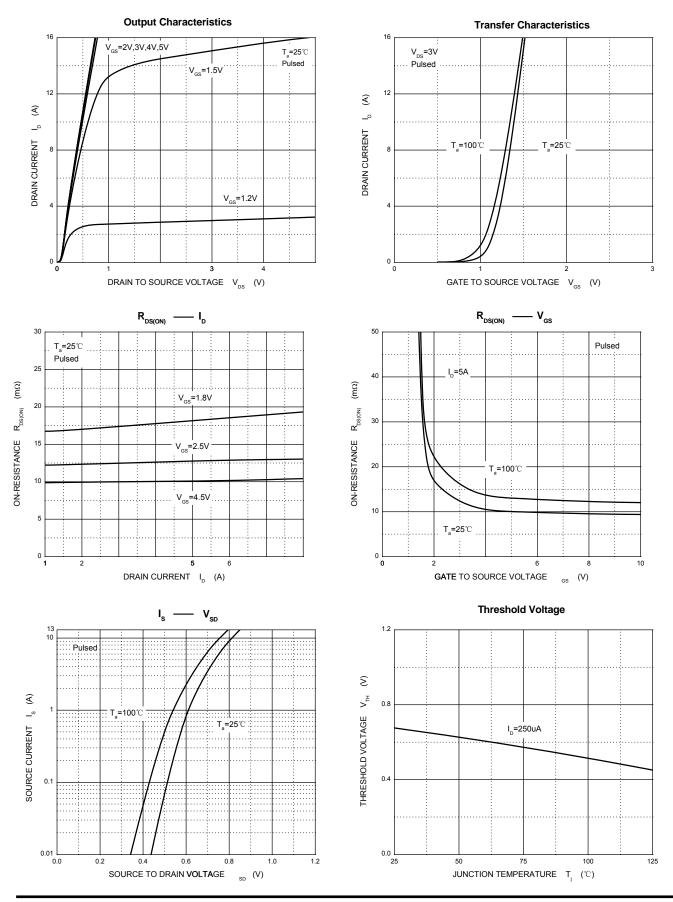
4. These parameters have no way to verify.



WSD2018DN22

N-Ch MOSFET

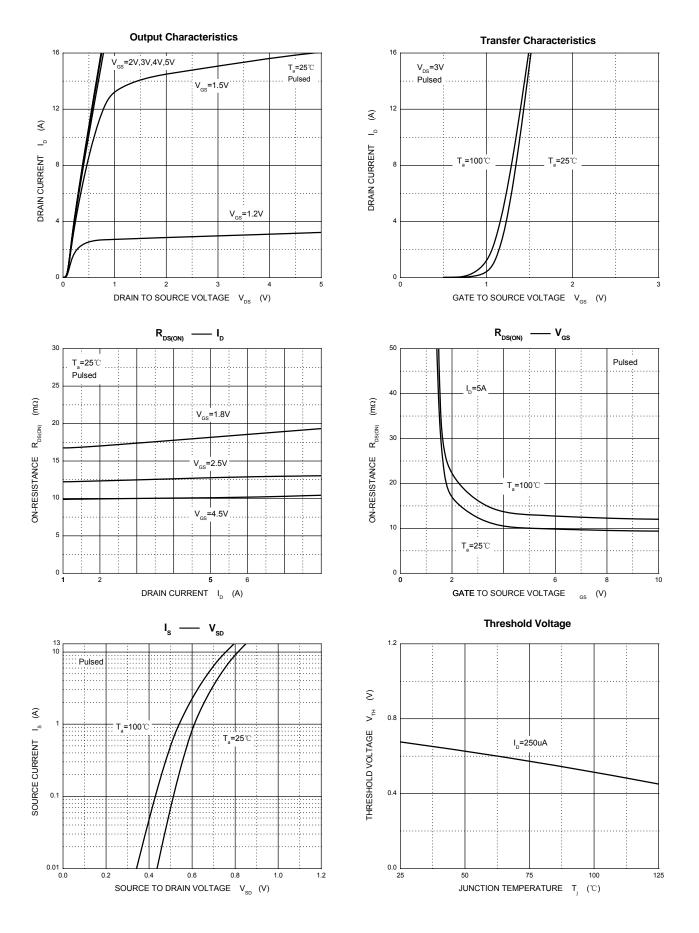
# **Typical Characteristics**





WSD2018DN22

## N-Ch MOSFET

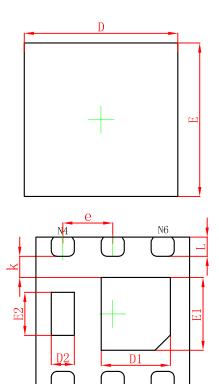




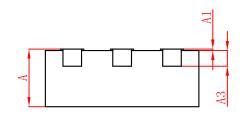
# WSD2018DN22

N-Ch MOSFET

# DFNWB2X2-6L-J Package Outline Dimensions



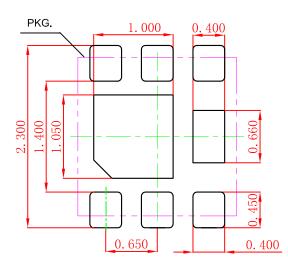
N3



Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	0.700	0.800		0.032	
A1	0.000	0.050	0.000	0.002	
A3	0.203	REF.	0.008	REF.	
D	1.924	2.076	0.076	0.082	
E	1.924	2.076	0.076	0.082	
D1	0.800	1.000	0.031	0.039	
E1	0.850	1.050	0.033	0.041	
D2	0.200	0.400	0.008	0.016	
E2	0.460	0.660	0.018	0.026	
k	0.200MIN.		0.200MIN. 0.008MIN.		
b	0.250	0.350	0.010	0.014	
е	0.650TYP.		0.026	TYP.	
L	0.174	0.326	0.007	0.013	

# DFNWB2X2-6L-J Suggested Pad Layout

N1



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:± 0.050mm.

3. The pad layout is for reference purposes only.



# Attention

1, Any and all Winsok power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your Winsok power representative nearest you before using any Winsok power products described or contained herein in such applications.

2, Winsok power assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all Winsok power products described or contained herein.

3, Specifications of any and all Winsok power products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

4, Winsok power Semiconductor CO., LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

5, In the event that any or all Winsok power products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

6, No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of Winsok power Semiconductor CO., LTD.

7, Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. Winsok power believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

8, Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the Winsok power product that you Intend to use.

9, this catalog provides information as of Sep.2014. Specifications and information herein are subject to change without notice.

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by Winsok manufacturer:

Other Similar products are found below :

614233C 648584F MCH3443-TL-E MCH6422-TL-E FDPF9N50NZ FW216A-TL-2W FW231A-TL-E APT5010JVR NTNS3A92PZT5G IRF100S201 JANTX2N5237 2SK2464-TL-E 2SK3818-DL-E FCA20N60\_F109 FDZ595PZ STD6600NT4G FSS804-TL-E 2SJ277-DL-E 2SK1691-DL-E 2SK2545(Q,T) D2294UK 405094E 423220D MCH6646-TL-E TPCC8103,L1Q(CM 367-8430-0972-503 VN1206L 424134F 026935X 051075F SBVS138LT1G 614234A 715780A NTNS3166NZT5G 751625C 873612G IRF7380TRHR IPS70R2K0CEAKMA1 RJK60S3DPP-E0#T2 RJK60S5DPK-M0#T0 APT5010JVFR APT12031JFLL APT12040JVR DMN3404LQ-7 NTE6400 JANTX2N6796U JANTX2N6784U JANTXV2N5416U4 SQM110N05-06L-GE3 SIHF35N60E-GE3